

STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Cancelled)**
2. **(Currently Amended)** An apparatus according to claim 421, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.
3. **(Currently Amended)** An apparatus according to claim 2, wherein said brush roller comprises an electrically conductive material.
4. **(Currently Amended)** An apparatus according to claim 3, wherein said brush roller comprises a polymer filled with an electrically-conductive material.
5. **(Currently Amended)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.
6. **(Currently Amended)** An apparatus according to claim 421, wherein said rotating wafer-cleaning member is part of said electrically-conductive path.
7. **(Currently Amended)** An apparatus according to claim 63, wherein said cleaning member is a rotational brush roller comprises a foam rubber cleaning portion.
8. **(Withdrawn and Currently Amended)** An apparatus according to claim 421, wherein said electrically-conductive electrical grounding path includes at least one contact that engages the article-microelectronics wafer at a location spaced from said rotating wafer-cleaning member during at least a portion of the time said rotating wafer-cleaning member is engaged with the article-microelectronics wafer.
9. **(Withdrawn and Currently Amended)** An apparatus according to claim 8, wherein said rotating wafer-cleaning member has a leading side and a trailing side and said at least one contact is located proximate one of said leading side and said trailing side.

10. **(Currently Amended)** A method of removing surface contaminants from a surface of an article a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:

- (a) providing a microelectronics wafer having a surface;
- (b) cleaning the said surface of the article said microelectronics wafer with a rotating wafer-cleaning member so as to remove at least some of the surface contaminants; and
- (b) c during at least part of the time that step (a) is being performed, contacting the article said microelectronics wafer with a conductive member connected to so as to create an electrical ground path between said surface and an electrical ground.

11. **(Currently Amended)** A method according to claim 10, wherein said rotating wafer-cleaning member is electrically conductive and step (b) includes contacting said rotating wafer-cleaning member with the article said microelectronics wafer.

12. **(Currently Amended)** A method according to claim 10, wherein step (a) includes contacting the said surface with said rotating wafer-cleaning member.

13. **(Currently Amended)** A method according to claim 12, wherein step (a) includes brushing the said surface with said rotating wafer-cleaning member.

14. **(Currently Amended)** A method according to claim 13, wherein step (a) includes rotating said cleaning member at least during the time said cleaning member is in contact with the surfacecontacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.

15. **(Withdrawn and Currently Amended)** A method according to claim 10, wherein step (b) includes contacting the article said microelectronics wafer with at least one contact spaced from said rotating wafer-cleaning member.

16. **(Withdrawn)** A method according to claim 15, wherein step (b) includes contacting said at least one contact with said surface.

17. **(Currently Amended)** A system for removing surface contaminants from a surface, comprising:

- (a) an electronic article a microelectronics wafer and having a surface;
- (b) a wafer-cleaning region receiving said microelectronics wafer;
- (b) a rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface;
- (e) an electrical ground; and
- (e) an electrically-conductive path extending from said article microelectronics wafer to said ground.

18. **(Currently Amended)** A system according to claim 17, wherein said rotating wafer-cleaning member comprises a rotational-brush roller having a non-filamentous cleaning surface.

19. **(Currently Amended)** A system according to claim 18, wherein said rotational-brush roller is part of said electrically-conductive path.

20. **(Withdrawn and Currently Amended)** A system according to claim 17, wherein said electrically-conductive path includes at least one contact that engages said electronic article microelectronics wafer at a location spaced from said rotating wafer-cleaning member during at least a portion of the time said cleaning member is engaged with said electronic article microelectronics wafer.

21. **(New)** An apparatus for cleaning surface contaminants from a microelectronics wafer, comprising:

- (a) a wafer cleaning region configured to receive a microelectronics wafer during cleaning;
- (b) a rotating wafer-cleaning member designed to contact the microelectronics wafer during cleaning so as to remove surface contaminants from the microelectronics wafer during cleaning; and
- (c) an electrical grounding path extending from the microelectronic wafer to an electrical ground when the apparatus is connected to the electrical ground.